查询BAS21HT1G供应商

BAS21HT1

Preferred Device

High Voltage Switching Diode

Features

• Pb-Free Packages are Available

ON

,24小时加急出货

ON Semiconductor®

专业PCB打样工厂

http://onsemi.com

HIGH VOLTAGE SWITCHING DIODE

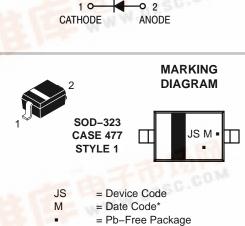


Symbol	Rating	Value	Unit
V _R	Continuous Reverse Voltage	250	Vdc
V _{RRM}	Repetitive Peak Reverse Voltage	250	Vdc
١ _F	Peak Forward Current	200	mAdc
I _{FM(surge)}	A(surge) Peak Forward Surge Current		mAdc

THERMAL CHARACTERISTICS

		and the second sec	
Symbol	mbol Characteristic		Unit
PD	Total Device Dissipation FR–5 Board, (Note 1) $T_A = 25^{\circ}C$	200	mW
516	Derate above 25°C	1.57	mW/°C
R _{0JA}	Thermal Resistance, Junction-to-Ambient	635	°C/W
T _J , T _{stg}	Γ _J , T _{stg} Junction and Storage Temperature Range		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability. 1. FR–5 Minimum Pad



(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
BAS21HT1	SOD-323	3000/Tape & Reel
BAS21HT1G	SOD-323 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

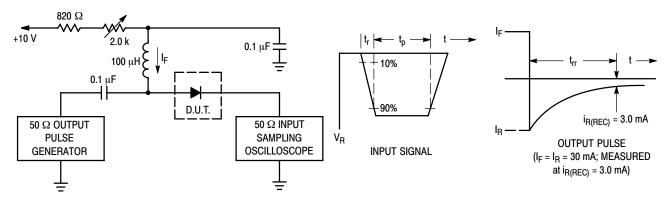
Preferred devices are recommended choices for future use and best overall value.

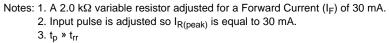


BAS21HT1

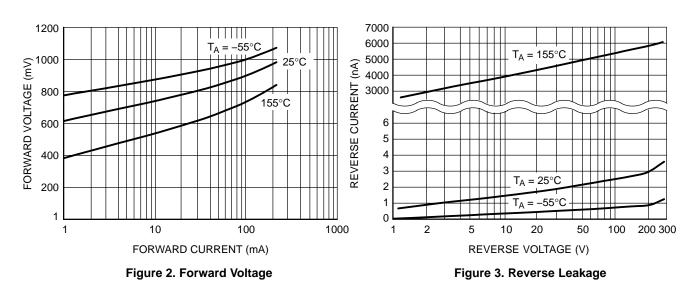
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	·			
Reverse Voltage Leakage Current $(V_R = 200 \text{ Vdc})$ $(V_R = 200 \text{ Vdc}, T_J = 150^{\circ}\text{C})$	I _R	-	0.1 100	μAdc
Reverse Breakdown Voltage (I _{BR} = 100 μAdc)	V _(BR)	250	-	Vdc
Forward Voltage (I _F = 100 mAdc) (I _F = 200 mAdc)	V _F		1000 1250	mV
Diode Capacitance ($V_R = 0$, f = 1.0 MHz)	C _D	-	5.0	pF
Reverse Recovery Time ($I_F = I_R = 30 \text{ mAdc}, R_L = 100 \Omega$)	t _{rr}	-	50	ns



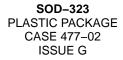


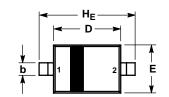


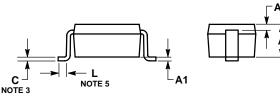


BAS21HT1

PACKAGE DIMENSIONS







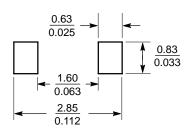
NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS.
- 2. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. 4.
- 5. DIMENSION L IS MEASURED FROM END OF RADIUS

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF		0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

STYLE 1: PIN 1. CATHODE 2. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and 💷 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILIC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILIC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILIC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative